Lighting Color Yellow Green

LNJ318C8TRA

Surface Mounting Chip LED

Dome-Lens Type

Absolute Maximum Ratings $T_a = 25^{\circ}C$

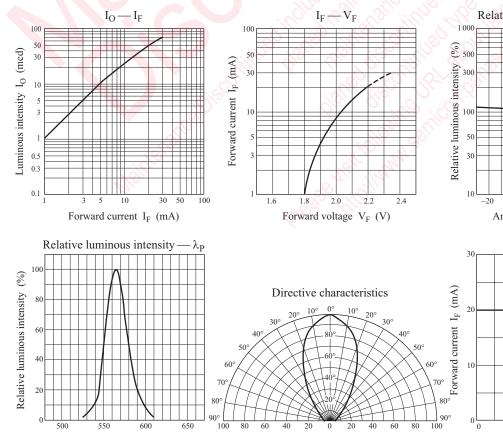
Parameter	Symbol	Rating	Unit	
Power dissipation	P _D	60	mW	
Forward current	I _F	20	mA	
Pulse forward current *	I _{FP}	60	mA	
Reverse voltage	V _R	4	v	
Operating ambient temperature	T _{opr}	-30 to +85	°C	
Storage temperature	T _{stg}	-40 to +100	°C	

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

Electro-Optical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol		Conditions	Min	Тур	Max	Unit
Luminous intensity *	I _O	$I_F = 10 \text{ mA}$	\$10°	10	25		mcd
Reverse current	I _R	$V_R = 4 V$	e dif			10	μΑ
Forward voltage	V _F	$I_F = 10 \text{ mA}$	Sol On		2.03	2.60	V
Peak emission wavelength	λ_{P}	$I_{\rm F} = 10 {\rm mA}$	North Co. Co.	X	565	S.	nm
Spectral half band width	Δλ	$I_{\rm F} = 10 {\rm mA}$	40m all all and	S	30		nm

Note) *: Measurement tolerance: ±20%

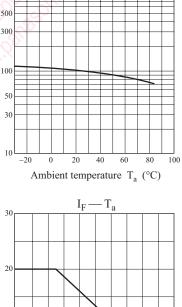


100

80 60

650

Relative luminous intensity Ta



20

40

60

Ambient temperature T_a (°C)

80

100

500

550

Peak emission wavelength λ_{P} (nm)

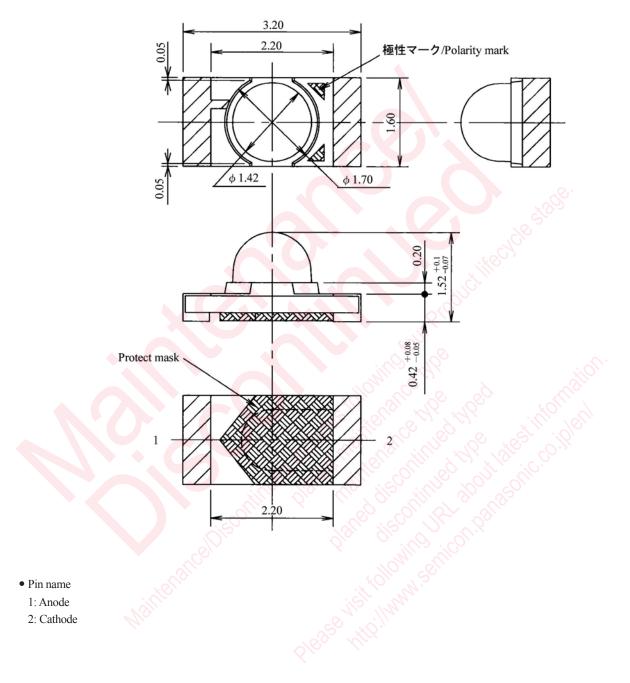
600

Relative luminous intensity (%)

40

80 100 Package (Unit: mm)

KLTLTN2K1800



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